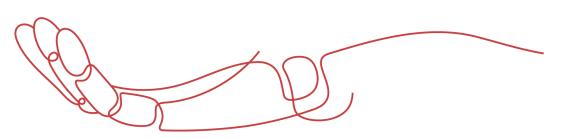




PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at







Datasheet

Sample

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

ESD Protection Diode Array

Features

- 150Watts peak pulse power (tp = 8/20's)
- SOT23-6 package
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (Cj=0.3pF typ. IO to IO)
- Protection one data/power line to:
- IEC 61000-4-2 ß12kV contact ß15kV air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 5A (8/20's)



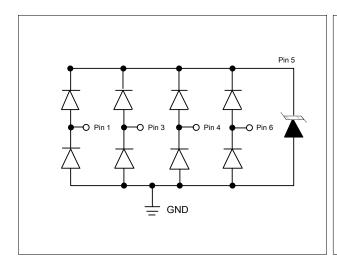
Applications

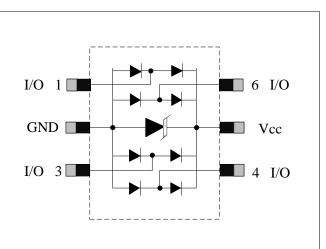
- Ethernet
- Digital Visual Interface (DVI)
- USB2.0
- Notebook and PC Computers

Mechanical Data

- SOT23-6 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

Schematic & PIN Configuration







Absolute Maximum Rating

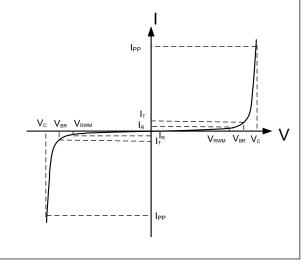
Rating	Symbol	Value	Units
Peak Pulse Power (t _p =8/20's)	P _{PP}	150	Watts
Peak Pulse Current (t _p =8/20's) (note1)	I _{pp}	5.0	А
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2	V _{ESD}	15 12	kV
(Contact) Lead Soldering Temperature	TL	260(10seconds)	$^{\circ}$ C
Junction Temperature	TJ	-55 to + 125	$^{\circ}$ C
Storage Temperature	T _{stg}	-55 to + 125	$^{\circ}$ C

Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				5.0	٧
Reverse Breakdown Voltage	V_{BR}	I _T =1mA	6			V
Reverse Leakage Current	I _R	V _{RWM} =5V,T=25℃			1.0	uA
Peak Pulse Current	I _{PP}	tp =8/20's			5.0	Α
Clamping Voltage	V _C	I _{PP} =5.0A,t _p =8/20's			16	V
Junction Capacitance	C _j	V _R = 0V, f = 1MHz IO to IO		0.3	0.45	
		V _R = 0V, f = 1MHz IO to GND		0.6	0.9	pF

Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter			
I PP	Maximum Reverse Peak Pulse Current			
Vc	Clamping Voltage @ IPP			
VRWM	Working Peak Reverse Voltage			
IR	Maximum Reverse Leakage Current @ V _{RWM}			
V _{BR}	Breakdown Voltage @ I⊤			
lτ	Test Current			





Typical Characteristic Curves

Fig.1 Peak Pulse Power Rating Curve

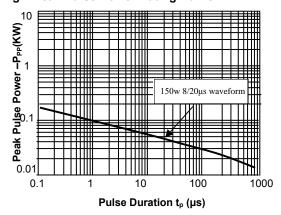


Fig.3 Pulse Waveform-8/20µs

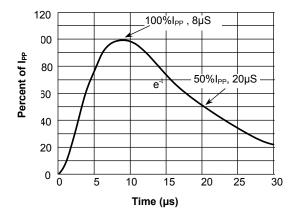


Fig.2 Pulse Derating Curve

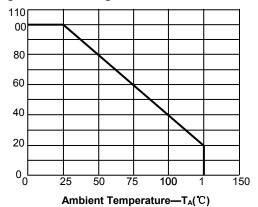
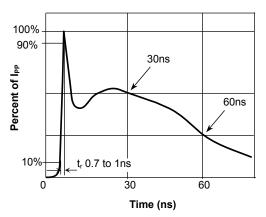


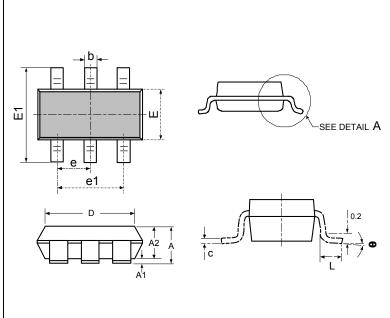
Fig.4 Pulse Waveform-ESD(IEC61000-4-2)





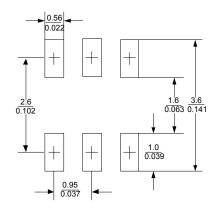
Outline Drawing - SOT23-6

PACKAGE OUTLINE



DIMENSIONS						
SYMBOL	INCHES		MILLIMETER			
	MIN	MAX	MIN	MAX		
Α	0.041	0.049	1.050	1.250		
A1	0.000	0.004	0.000	0.100		
A2	0.041	0.045	1.050	1.150		
D	0.111	0.119	2.820	3.020		
E	0.059	0.067	1.500	1.700		
E1	0.104	0.116	2.650	2.950		
b	0.012	0.020	0.300	0.500		
е	0.037(BSC)		0.950(BSC)			
e1	0.071	0.079	1.800	2.000		
L	0.012	0.024	0.300	0.600		
θ	0°	8°	0°	8°		





Notes

1. This land pattern is for reference purposes only consult your manufacturing group to ensure your company's manufacturing guidelines are met.



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